

PLATING OF COPPER ON SEMICONDUCTORS*Abstract of the Disclosure*

Monovalent copper plating baths are used to metallize current tracks of the front side or emitter side of semiconductor wafers. Copper is selectively deposited on the current tracks by electrolytic plating or LIP. Additional metallization of the current tracks may be done using conventional metal plating baths. The metalized semiconductors may be used in the manufacture of photovoltaic devices.

No Figure